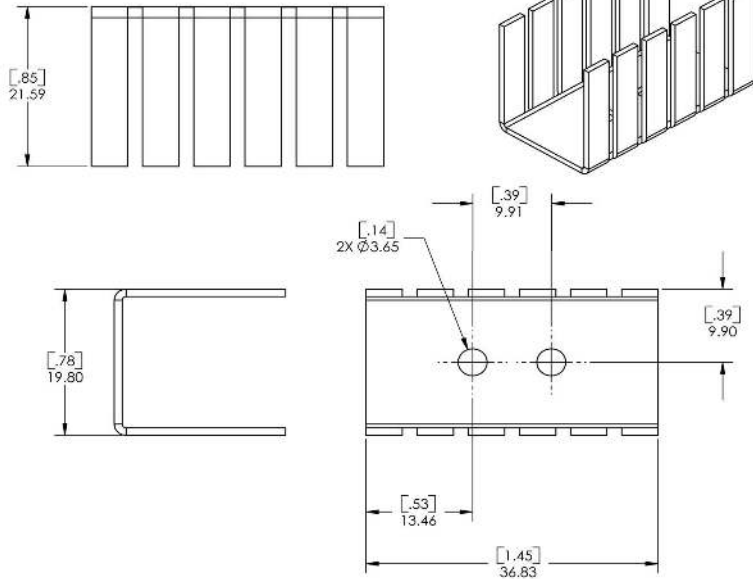
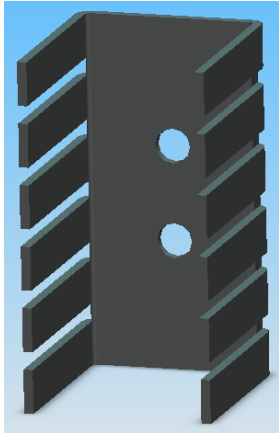


# Board Level Heat Sinks



ThermaFlo

P/N: 821702B00000



## PRODUCT SPECIFICATIONS

- Devices: TO-220
- Size: 36.8 x 19.8 x 21.6mm
- Material: Aluminum, 1.0mm Thick
- Type: Stamped
- Finish: Black Anodized
- PCB Mounting: Solderable Device Leads
- Package: Bulk
- Accessories: Hardware & Thermal Interface Material

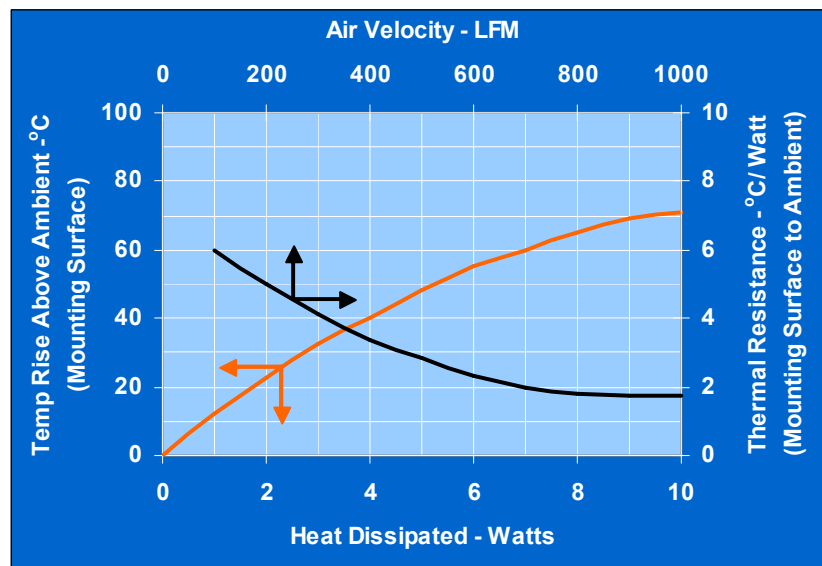
## FEATURES & BENEFITS

- Multiple Holes for Device Attachment
- Dual Device Cooling Heat Sink
- RoHS Compliant



## Customized Heat Sinks

- Specialized Plating
- Specialized Body Configurations
- Contact Applications Engineering



TO-220

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